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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	68 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc711t-04-ss

TABLE 1-1: PIC16C71X FAMILY OF DEVICES

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72[(1)]
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	1K	2K	2K	—
	ROM Program Memory (14K words)	—	—	—	—	—	2K
	Data Memory (bytes)	36	36	68	128	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	—	—	—	—	1	1
	Serial Port(s) (SPI/I^{2}C, USART)	—	—	—	—	SPI/I^{2}C	SPI/I^{2}C
	Parallel Slave Port	—	—	—	—	—	—
	A/D Converter (8-bit) Channels	4	4	4	4	5	5
Features	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	2.5-6.0	3.0-6.0	2.5-6.0	2.5-5.5	2.5-6.0	3.0-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP

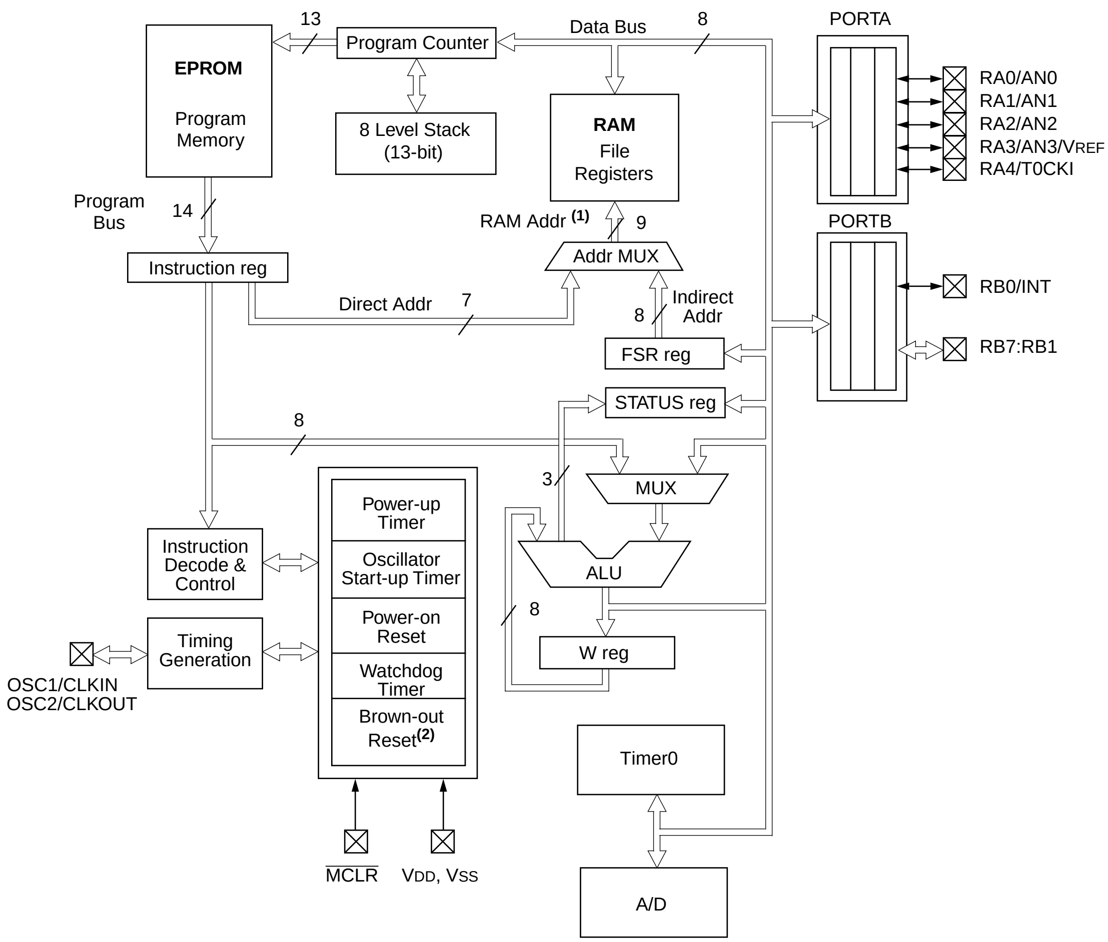
		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K
	Data Memory (bytes)	192	192	376	376
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	2	2	2	2
	Serial Port(s) (SPI/I^{2}C, USART)	SPI/I^{2}C, USART	SPI/I^{2}C, USART	SPI/I^{2}C, USART	SPI/I^{2}C, USART
	Parallel Slave Port	—	Yes	—	Yes
	A/D Converter (8-bit) Channels	5	8	5	8
Features	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.

FIGURE 3-1: PIC16C71X BLOCK DIAGRAM

Device	Program Memory	Data Memory (RAM)
PIC16C710	512 x 14	36 x 8
PIC16C71	1K x 14	36 x 8
PIC16C711	1K x 14	68 x 8
PIC16C715	2K x 14	128 x 8



Note 1: Higher order bits are from the STATUS register.
2: Brown-out Reset is not available on the PIC16C71.

FIGURE 4-5: PIC16C711 REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h		PCON	87h
08h	ADCON0	ADCON1	88h
09h	ADRES	ADRES	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch – 4Fh	General Purpose Register	General Purpose Register Mapped in Bank 0(2)	8Ch – CFh
50h – 7Fh			D0h – FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

2: These locations are unimplemented in Bank 1. Any access to these locations will access the corresponding Bank 0 register.

FIGURE 4-6: PIC16C715 REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h – 7Fh	General Purpose Register	General Purpose Register	A0h – BFh
			C0h – FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

```
ORG 0x500
BSF    PCLATH,3   ;Select page 1 (800h-FFFh)
BCF    PCLATH,4   ;Only on >4K devices
CALL   SUB1_P1    ;Call subroutine in
       :          ;page 1 (800h-FFFh)
       :
       :
ORG 0x900
SUB1_P1:          ;called subroutine
       :          ;page 1 (800h-FFFh)
       :
RETURN            ;return to Call subroutine
                  ;in page 0 (000h-7FFh)
```

4.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

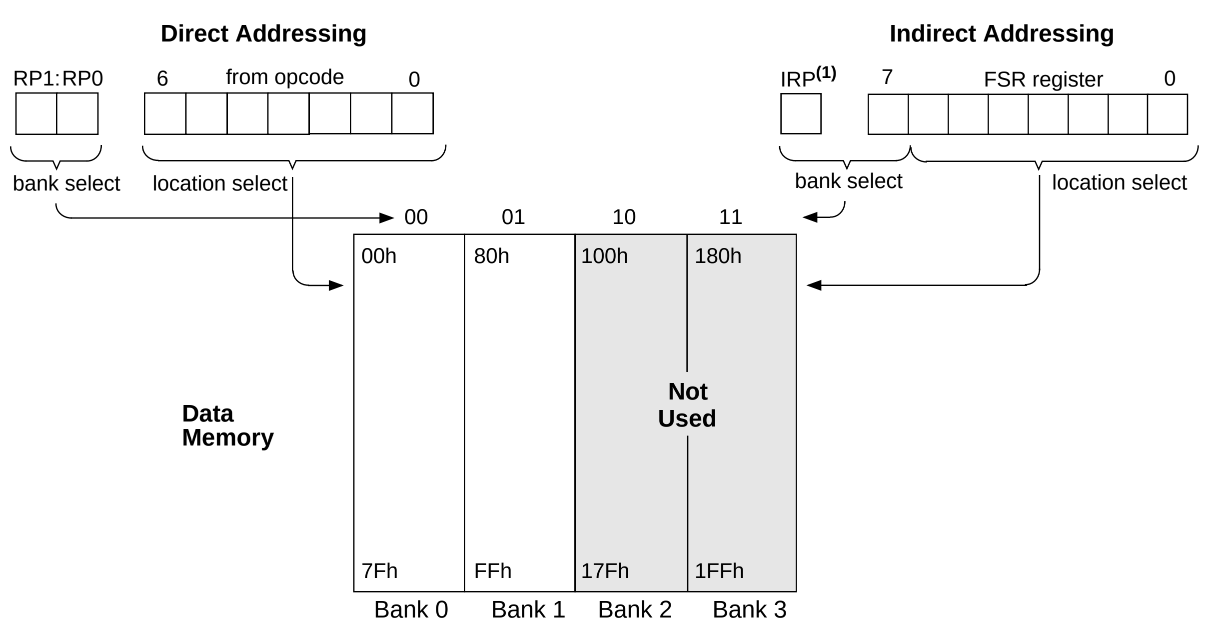
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = '0') will read 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-15. However, IRP is not used in the PIC16C71X devices.

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 4-2.

EXAMPLE 4-2: INDIRECT ADDRESSING

```
         movlw  0x20   ;initialize pointer
         movwf  FSR    ;to RAM
NEXT     clrf   INDF   ;clear INDF register
         incf   FSR,F  ;inc pointer
         btfss  FSR,4  ;all done?
         goto   NEXT   ;no clear next
CONTINUE
         :              ;yes continue
```

FIGURE 4-15: DIRECT/INDIRECT ADDRESSING



For register file map detail see Figure 4-4.

Note 1: The RP1 and IRP bits are reserved, always maintain these bits clear.

5.0 I/O PORTS

Applicable Devices	710	71	711	715

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

PORTA is a 5-bit latch.

The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as output or input.

Setting a TRISA register bit puts the corresponding output driver in a hi-impedance mode. Clearing a bit in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore a write to a port implies that the port pins are read, this value is modified, and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin.

Other PORTA pins are multiplexed with analog inputs and analog VREF input. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

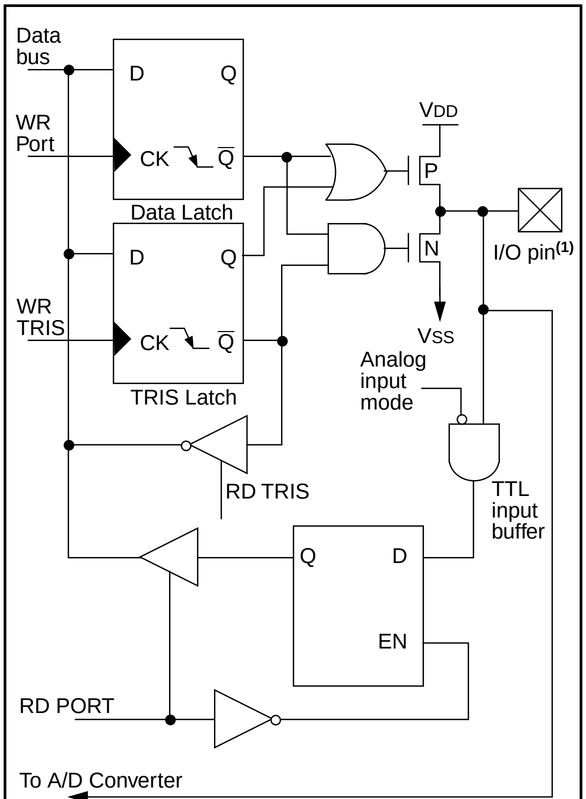
Note: On a Power-on Reset, these pins are configured as analog inputs and read as '0'.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

EXAMPLE 5-1: INITIALIZING PORTA

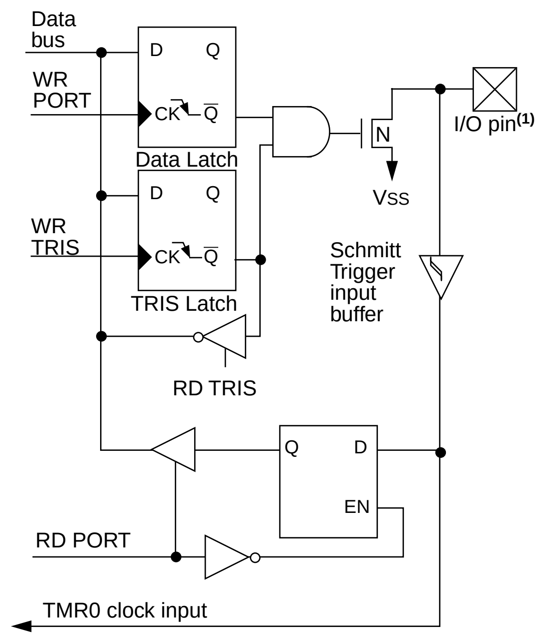
```
BCF     STATUS, RP0   ;
CLRF    PORTA         ; Initialize PORTA by
                      ; clearing output
                      ; data latches
BSF     STATUS, RP0   ; Select Bank 1
MOVLW   0xCF          ; Value used to
                      ; initialize data
                      ; direction
MOVWF   TRISA         ; Set RA<3:0> as inputs
                      ; RA<4> as outputs
                      ; TRISA<7:5> are always
                      ; read as '0'.
```

FIGURE 5-1: BLOCK DIAGRAM OF RA3:RA0 PINS



Note 1: I/O pins have protection diodes to VDD and VSS.

FIGURE 5-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



Note 1: I/O pin has protection diodes to VSS only.

7.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (C_{HOLD}) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-5. The source impedance (R_S) and the internal sampling switch (R_{SS}) impedance directly affect the time required to charge the capacitor C_{HOLD}. The sampling switch (R_{SS}) impedance varies over the device voltage (V_{DD}), Figure 7-5. The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ**. After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

EQUATION 7-1: A/D MINIMUM CHARGING TIME

$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \cdot (1 - e^{(-T_{CAP}/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$

Given: $V_{HOLD} = (V_{REF}/512)$, for 1/2 LSb resolution

The above equation reduces to:

$T_{CAP} = -(51.2 \text{ pF})(1 \text{ k}\Omega + R_{SS} + R_S) \ln(1/511)$

Example 7-1 shows the calculation of the minimum required acquisition time T_{ACQ}. This calculation is based on the following system assumptions.

$C_{HOLD} = 51.2$ pF

$R_s = 10$ kΩ

1/2 LSb error

$V_{DD} = 5V \rightarrow R_{ss} = 7$ kΩ

Temp (application system max.) = 50°C

$V_{HOLD} = 0$ @ t = 0

> **Note 1:** The reference voltage (V_{REF}) has no effect on the equation, since it cancels itself out.
>
> **Note 2:** The charge holding capacitor (C_{HOLD}) is not discharged after each conversion.
>
> **Note 3:** The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.
>
> **Note 4:** After a conversion has completed, a $2.0T_{AD}$ delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

EXAMPLE 7-1: CALCULATING THE MINIMUM REQUIRED AQUISITION TIME

T_{ACQ} = Amplifier Settling Time + Holding Capacitor Charging Time + Temperature Coefficient

T_{ACQ} = 5 µs + T_{CAP} + [(Temp - 25°C)(0.05 µs/°C)]

T_{CAP} = $-C_{HOLD}$ (R_{IC} + R_{SS} + R_S) ln(1/511)

-51.2 pF (1 kΩ + 7 kΩ + 10 kΩ) ln(0.0020)

-51.2 pF (18 kΩ) ln(0.0020)

-0.921 µs (-6.2364)

5.747 µs

T_{ACQ} = 5 µs + 5.747 µs + [(50°C - 25°C)(0.05 µs/°C)]

10.747 µs + 1.25 µs

11.997 µs

FIGURE 7-5: ANALOG INPUT MODEL

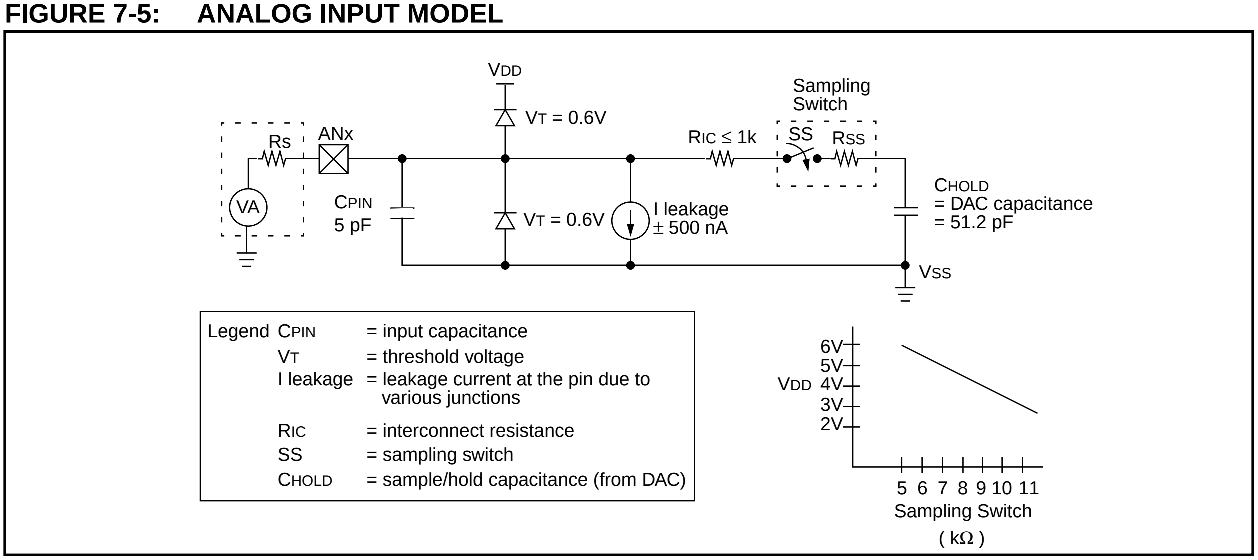


TABLE 8-7: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C71

$\overline{TO}$	$\overline{PD}$	
1	1	Power-on Reset
0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
0	1	WDT Reset
0	0	WDT Wake-up
u	u	$\overline{MCLR}$ Reset during normal operation
1	0	$\overline{MCLR}$ Reset during SLEEP or interrupt wake-up from SLEEP

TABLE 8-8: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C710/711

$\overline{POR}$	$\overline{BOR}$	$\overline{TO}$	$\overline{PD}$	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
0	x	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	0	x	x	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{MCLR}$ Reset during normal operation
1	1	1	0	$\overline{MCLR}$ Reset during SLEEP or interrupt wake-up from SLEEP

TABLE 8-9: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C715

$\overline{PER}$	$\overline{POR}$	$\overline{BOR}$	$\overline{TO}$	$\overline{PD}$	
1	0	x	1	1	Power-on Reset
x	0	x	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
x	0	x	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	1	0	x	x	Brown-out Reset
1	1	1	0	1	WDT Reset
1	1	1	0	0	WDT Wake-up
1	1	1	u	u	$\overline{MCLR}$ Reset during normal operation
1	1	1	1	0	$\overline{MCLR}$ Reset during SLEEP or interrupt wake-up from SLEEP
0	1	1	1	1	Parity Error Reset
0	0	x	x	x	Illegal, $\overline{PER}$ is set on POR
0	x	0	x	x	Illegal, $\overline{PER}$ is set on BOR

8.5 Interrupts

Applicable Devices	710	71	711	715

The PIC16C71X family has 4 sources of interrupt.

Interrupt Sources
External interrupt RB0/INT
TMR0 overflow interrupt
PORTB change interrupts (pins RB7:RB4)
A/D Interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

> **Note:** Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 8-19). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

> **Note:** For the PIC16C71
> If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the `RETFIE` instruction). The events that would cause this to occur are:
>
> 1. An instruction clears the GIE bit while an interrupt is acknowledged.
> 2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
> 3. The Interrupt Service Routine completes with the execution of the `RETFIE` instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.
>
> Perform the following to ensure that interrupts are globally disabled:

```
LOOP BCF   INTCON, GIE  ; Disable global
                        ;  interrupt bit
     BTFSC INTCON, GIE  ; Global interrupt
                        ;   disabled?
     GOTO  LOOP         ; NO, try again
        :               ;   Yes, continue
                        ;   with program
                        ;   flow
```

INCFSZ **Increment f, Skip if 0**

Syntax:	[*label*] INCFSZ f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) + 1 $\rightarrow$ (dest), skip if result = 0
Status Affected:	None

Encoding:

00	1111	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead making it a 2TCY instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to dest

If Skip: (2nd Cycle)

Q1	Q2	Q3	Q4
NOP	NOP	NOP	NOP

Example

```
HERE      INCFSZ     CNT, 1
          GOTO      LOOP
CONTINUE •
         •
         •
```

Before Instruction
PC = address HERE

After Instruction
CNT = CNT + 1
if CNT= 0,
PC = address CONTINUE
if CNT≠ 0,
PC = address HERE +1

IORLW **Inclusive OR Literal with W**

Syntax:	[*label*] IORLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .OR. k $\rightarrow$ (W)
Status Affected:	Z

Encoding:

11	1000	kkkk	kkkk

Description: The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example

```
IORLW   0x35
```

Before Instruction
W = 0x9A

After Instruction
W = 0xBF
Z = 1

TABLE 10-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12C5XX	PIC14000	PIC16C5X	PIC16CXXX	PIC16C6X	PIC16C7XX	PIC16C8X	PIC16C9XX	PIC17C4X	PIC17C75X	24CXX 25CXX 93CXX	HCS200 HCS300 HCS301
Emulator Products	PICMASTER®/ PICMASTER-CE In-Circuit Emulator	✔	✔	✔	✔	✔	✔	✔	✔	✔	Available 3Q97		
	ICEPIC Low-Cost In-Circuit Emulator	✔		✔	✔	✔	✔	✔					
Software Tools	MPLAB™ Integrated Development Environment	✔	✔	✔	✔	✔	✔	✔	✔	✔	✔		
	MPLAB™ C Compiler	✔	✔	✔	✔	✔	✔	✔	✔	✔	✔		
	*fuzzy*TECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	✔	✔	✔	✔	✔	✔	✔	✔	✔			
	MP-DriveWay™ Applications Code Generator			✔	✔	✔	✔	✔		✔			
	Total Endurance™ Software Model											✔	
Programmers	PICSTART® Lite Ultra Low-Cost Dev. Kit			✔		✔	✔	✔					
	PICSTART® Plus Low-Cost Universal Dev. Kit	✔	✔	✔	✔	✔	✔	✔	✔	✔	✔		
	PRO MATE® II Universal Programmer	✔	✔	✔	✔	✔	✔	✔	✔	✔	✔	✔	✔
	KEELOQ® Programmer												✔
Demo Boards	SEEVAL® Designers Kit											✔	
	PICDEM-1			✔	✔			✔		✔			
	PICDEM-2					✔	✔						
	PICDEM-3								✔				
	KEELOQ® Evaluation Kit												✔

Applicable Devices	710	71	711	715

11.3 DC Characteristics: PIC16C710-04 (Commercial, Industrial, Extended)

PIC16C711-04 (Commercial, Industrial, Extended)
PIC16C710-10 (Commercial, Industrial, Extended)
PIC16C711-10 (Commercial, Industrial, Extended)
PIC16C710-20 (Commercial, Industrial, Extended)
PIC16C711-20 (Commercial, Industrial, Extended)
PIC16LC710-04 (Commercial, Industrial, Extended)
PIC16LC711-04 (Commercial, Industrial, Extended)

DC CHARACTERISTICS		**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0˚C ≤ TA ≤ +70˚C (commercial) -40˚C ≤ TA ≤ +85˚C (industrial) -40˚C ≤ TA ≤ +125˚C (extended) Operating voltage VDD range as described in DC spec Section 11.1 and Section 11.2.					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{\text{MCLR}}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	For entire VDD range
D042	$\overline{\text{MCLR}}$, RB0/INT		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	µA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{\text{MCLR}}$, RA4/T0CKI		-	-	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	710	71	711	715

11.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

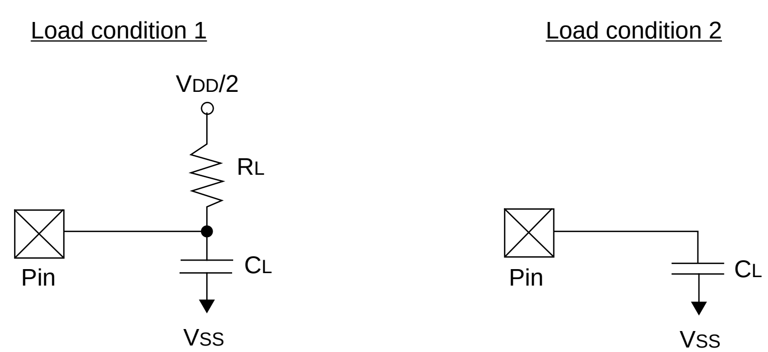
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance

FIGURE 11-1: LOAD CONDITIONS



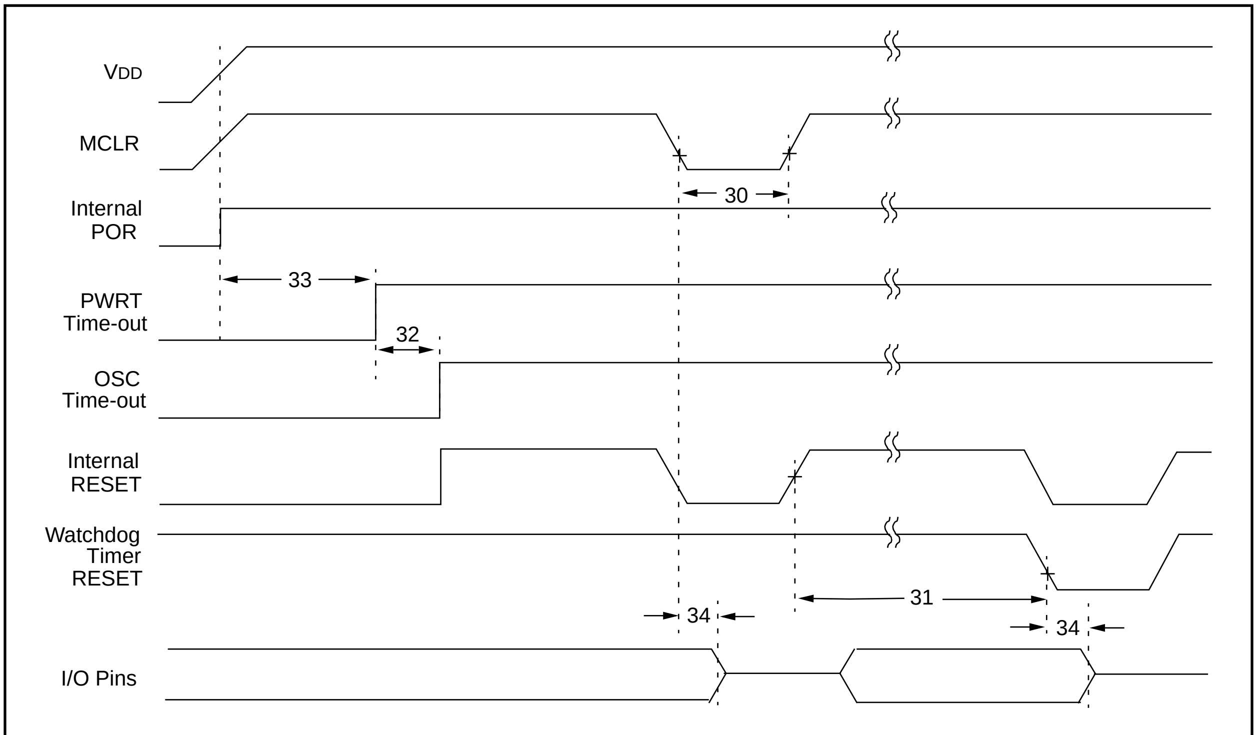
R_L = 464Ω

C_L = 50 pF for all pins except OSC2

15 pF for OSC2 output

Applicable Devices	710	71	711	715

FIGURE 11-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 11-1 for load conditions.

FIGURE 11-5: BROWN-OUT RESET TIMING

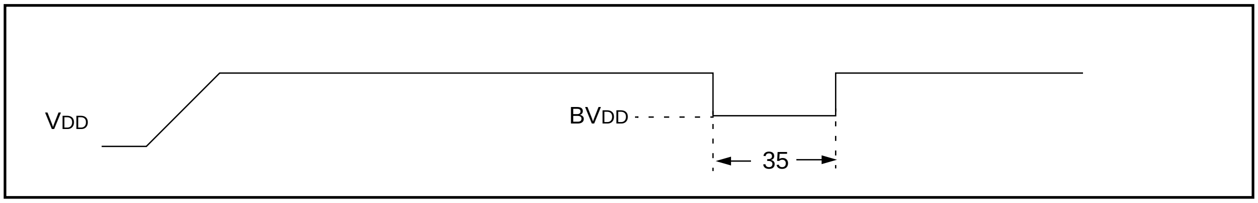


TABLE 11-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	1	—	—	µs	VDD = 5V, -40˚C to +125˚C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5V, -40˚C to +125˚C
32	Tost	Oscillation Start-up Timer Period	—	1024TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power up Timer Period	28*	72	132*	ms	VDD = 5V, -40˚C to +125˚C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	1.1	µs	
35	TBOR	Brown-out Reset pulse width	100	—	—	µs	3.8V ≤ VDD ≤ 4.2V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	710	71	711	715

13.5 Timing Diagrams and Specifications

FIGURE 13-2: EXTERNAL CLOCK TIMING

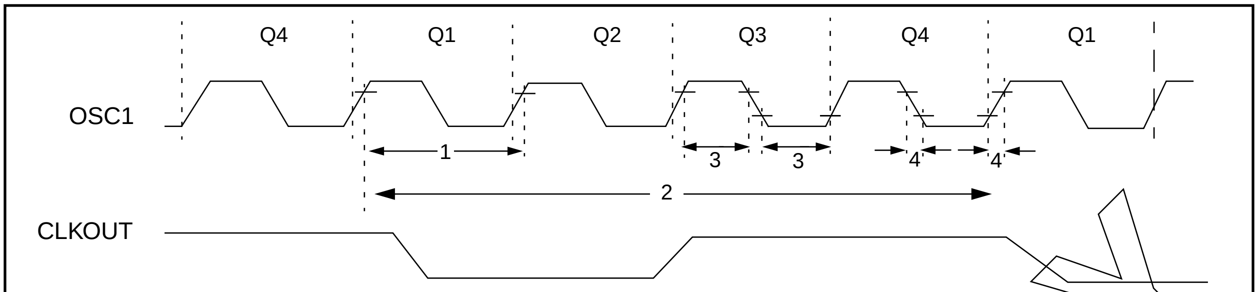


TABLE 13-2: CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fos	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT osc mode
			DC	—	4	MHz	HS osc mode (PIC16C715-04)
			DC	—	20	MHz	HS osc mode (PIC16C715-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	4	MHz	HS osc mode (PIC16C715-04)
			4	—	10	MHz	HS osc mode (PIC16C715-10)
			4	—	20	MHz	HS osc mode (PIC16C715-20)
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (PIC16C715-04)
			100	—	—	ns	HS osc mode (PIC16C715-10)
			50	—	—	ns	HS osc mode (PIC16C715-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (PIC16C715-04)
			100	—	250	ns	HS osc mode (PIC16C715-10)
			50	—	250	ns	HS osc mode (PIC16C715-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	—	DC	ns	TCY = 4/FOSC
3	TosL, TosH	**External Clock in (OSC1) High or Low Time**	50	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			10	—	—	ns	HS oscillator
4	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C715.

Applicable Devices	710	71	711	715

15.3 DC Characteristics: PIC16C71-04 (Commercial, Industrial) PIC16C71-20 (Commercial, Industrial) PIC16LC71-04 (Commercial, Industrial)

DC CHARACTERISTICS		**Standard Operating Conditions (unless otherwise stated)** OOperating temperature 0˚C ≤ TA ≤ +70˚C (commercial) -40˚C ≤ TA ≤ +85˚C (industrial) Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15V	V	For entire VDD range
D031	with Schmitt Trigger buffer		VSS	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D032	$\overline{MCLR}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports (Note 4)	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD		For entire VDD range
D041	with Schmitt Trigger buffer		0.85VDD	-	VDD		For entire VDD range
D042	$\overline{MCLR}$, RB0/INT		0.85VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	†400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	μA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	μA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	-	-	V	IOH = -3.0mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	-	-	V	IOH = -1.3mA, VDD = 4.5V, -40°C to +85°C
D130*	**Open-Drain High Voltage**	VOD	-	-	14	V	RA4 pin

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC16C71 be driven with external clock in RC mode.

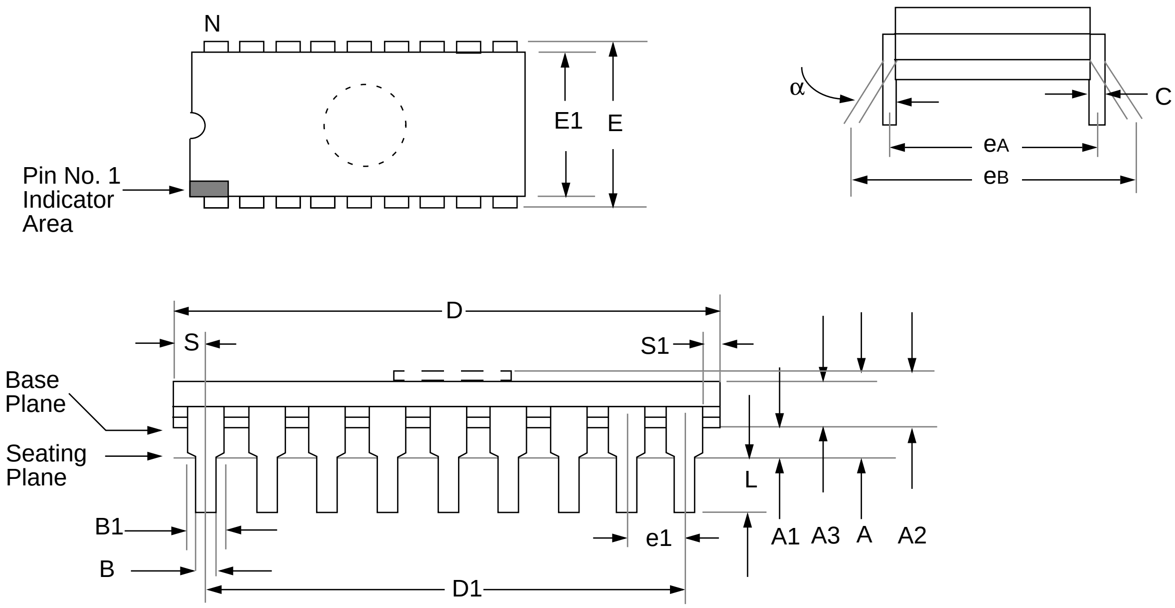
2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: PIC16C71 Rev. "Ax" INT pin has a TTL input buffer. PIC16C71 Rev. "Bx" INT pin has a Schmitt Trigger input buffer.

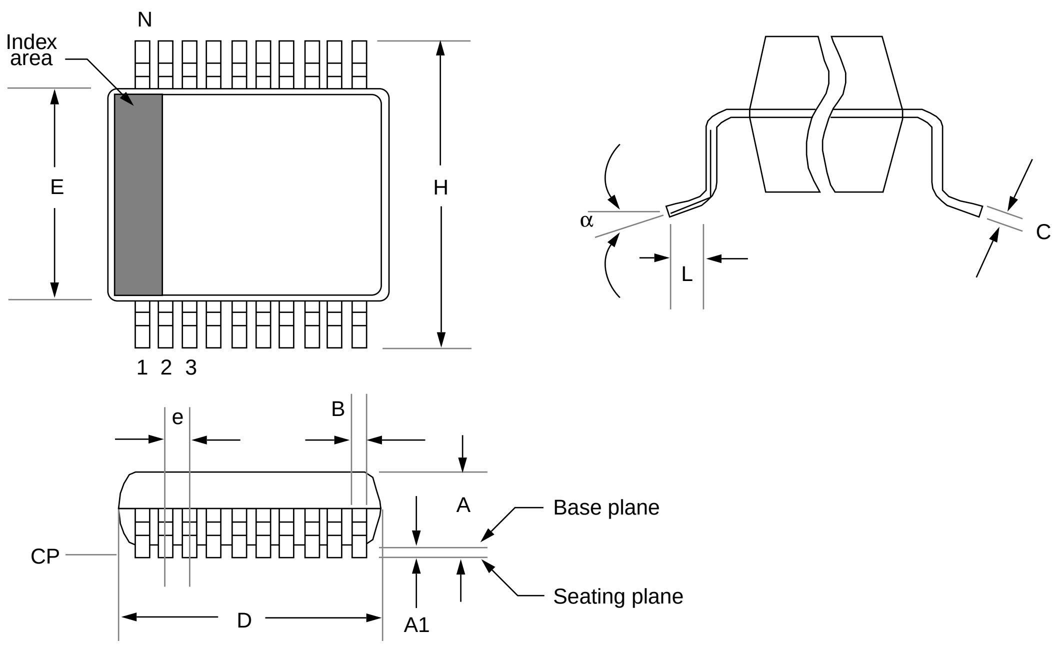
17.0 PACKAGING INFORMATION

17.1 18-Lead Ceramic CERDIP Dual In-line with Window (300 mil) (JW)



Package Group: Ceramic CERDIP Dual In-Line (CDP)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	—	5.080		—	0.200	
A1	0.381	1.7780		0.015	0.070	
A2	3.810	4.699		0.150	0.185	
A3	3.810	4.445		0.150	0.175	
B	0.355	0.585		0.014	0.023	
B1	1.270	1.651	**Typical**	0.050	0.065	**Typical**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	22.352	23.622		0.880	0.930	
D1	20.320	20.320	**Reference**	0.800	0.800	**Reference**
E	7.620	8.382		0.300	0.330	
E1	5.588	7.874		0.220	0.310	
e1	2.540	2.540	**Reference**	0.100	0.100	**Reference**
eA	7.366	8.128	**Typical**	0.290	0.320	**Typical**
eB	7.620	10.160		0.300	0.400	
L	3.175	3.810		0.125	0.150	
N	18	18		18	18	
S	0.508	1.397		0.020	0.055	
S1	0.381	1.270		0.015	0.050	

17.4 20-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)



Package Group: Plastic SSOP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
B	0.250	0.380		0.010	0.015	
C	0.130	0.220		0.005	0.009	
D	7.070	7.330		0.278	0.289	
E	5.200	5.380		0.205	0.212	
e	0.650	0.650	**Reference**	0.026	0.026	**Reference**
H	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
N	20	20		20	20	
CP	-	0.102		-	0.004	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25m/m (0.010”) per side. D1 and E1 dimensions including mold mismatch.
2: Dimension “b” does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08m/m (0.003”)max.
3: This outline conforms to JEDEC MS-026.

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